

高潔淨泛用型全氟化產品 High purity FFKM product, general purpose

- 適合在NF3、O2、CF4等電漿環境下使用，比起一般高潔淨型產品，對於在嚴苛的化學及電漿環境下使用，擁有更為優異的表現
Applied in NF3 or O2 CF4 plasma gas process.
Compared with normal high purity products, it shown a remarkable and stable feature in plasma and chemical environment
- 各項特性均有優異的表現，適合廣泛使用在各式製程
Excellent performance on every process.
- 產品之最後包裝與清潔均於無塵室內完成
Cleanroom packaging and cleaning.



ea 特性與優點 FEATURE

優異的物理特性
Excellent physical property
良好的不沾粘性
Good non-stick characteristics
對各式電漿環境有極優良的抗性
Excellent resistance to plasma environment
對O2 NF3 等電漿環境有良好的抗性
Extremely O2 resistance and NF3 plasma stability
對各式化學溶劑有極優良的抗性
Excellent resistance to solvents and chemicals

ea 典型物理特性 PROPERTY

硬度(Shore A)	74
顏色(Color)	White
模數(100 % Modulus , Mpa)	4.8
拉伸強度(Tensile strength at Break, Mpa)	11.4
延伸率(Elongation at Break, %)	195
壓縮變形率(Compression set 70 hr @ 204°C)	24.2
建議最高連續使用溫度(Temp. , °C)	250

ea 建議應用位置 APPLIED POSITION

反應槽密封件(Chamber Seals)
管線接頭密封件(Fitting Seals)
氣體管線密封件(Gas Inlet/Outlet Pumping Line Seals)
閥件密封件(Valve Seals)

ea 建議應用製程 APPLIED PROCESS

乾式蝕刻(Dry Etch)
濕式蝕刻(Wet Etch Acid,Base)
擴散(Diffusion)
離子植入(Ion Implant)
快速回火(RTP)
濕式去光阻(Wet Stripping Solvents)
濕式清潔(Wet Cleaning UPDI)